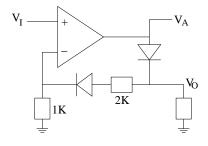
EE 321 Analog Electronics, Fall 2009 Exam 2 October 21, 2009

Rules: This is a closed-book test. You may use pen, paper, and calculator. The exam will last 50 minutes. Each problem counts equally toward your grade. None of the problems require long calculations.

(1) DIODE CIRCUIT. For the following circuit, assume 0.7 V across a forward biased diode, and op-amp rail limits of $L_{\pm} = \pm 9$ V. (a) Give expressions for V_A and V_O as a function of V_I . (b) plot V_A , and V_O as a function of V_I in the [-5 V; 5 V] interval.



(a)

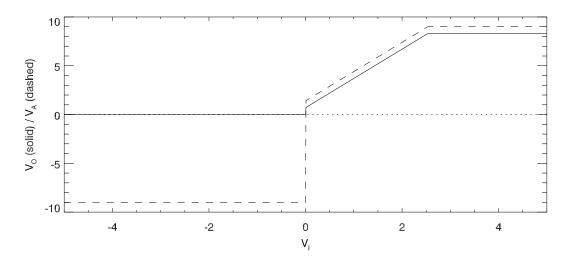
$$V_{O} = \begin{cases} 0 & V_{I} \le 0\\ 3V_{I} + V_{D} & 0 < V_{I} \end{cases}$$

but with clipping $V_O < L_+ - V_D$

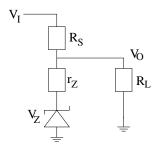
$$V_A = \begin{cases} L_{-} & V_I \le 0\\ 3V_I + 2V_D & 0 < V_I \end{cases}$$

but with clipping $V_O < L_+$

(b) The plot is here:



(2) ZENER VOLTAGE REGULATOR. The following circuit (with the Zener modeled as an ideal Zener in series with a small resistance r_Z) has $V_I = 10 \text{ V}$, $R_S = 1 \text{ k}\Omega$, $r_Z = 50 \Omega$, and $V_Z = 5.6 \text{ V}$, (a) what is the largest value of V_o ? (b) For what value of R_L does regulation cease (current through Zener goes to zero).



(a) The largest value of V_O occurs when all the current passes through r_z , which corresponds to $R_L \to \infty$.

$$V_{\rm O,max} = V_Z + r_z I_Z$$

where

$$I_Z = \frac{V_I - V_Z}{R_S + r_z}$$

Inserting

$$V_{\rm O,max} = V_Z + r_Z \frac{V_I - V_Z}{R_s + r_z}$$

Now inserting values we get

$$V_{\rm O,max} = 5.6 + 50 \frac{10 - 5.6}{10^3 + 50} = 5.81 \,\rm V$$

(b) Regulation ceases when the voltage drop across R_L is reduced to V_Z , and no current flows through the Zener diode,

$$IR_L = V_Z$$

with

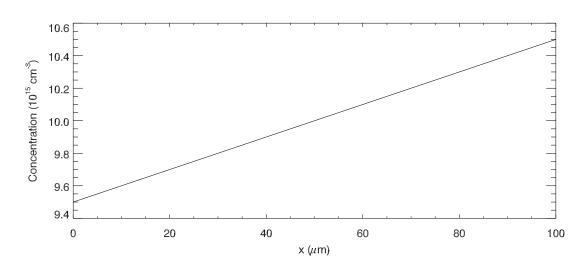
$$I = \frac{V_I}{R_s + R_L}.$$

Inserting

$$V_I \frac{R_L}{R_s + R_L} = V_Z$$

$$R_L = \frac{V_Z R_s}{V_I - V_Z} = \frac{5.6 \times 10^3}{10 - 5.6} = 1273 \,\Omega$$

(3) SEMICONDUCTOR. A bar of n-type semiconductor of length $L = 100 \,\mu\text{m}$ has a electron concentration which increases linearly from $9.5 \times 10^{15} \,\text{cm}^{-3}$ at the left end (x = 0) to $1.05 \times 10^{16} \,\text{cm}^{-3}$ at the right end (x = L). Ignore minority carriers. (a) Plot the electron concentration as a function of position in the semiconductor. (b) What is the size and direction of the diffusion current in the material? (c) The gradient can be maintained by applying a opposing drift current. What size and polarity of voltage should be applied? (To simplify the math you may assume constant number density across the slab).



(a) Plot of electron number density

(b) The electron diffusion current in the positive x-direction is

$$J_n = q D_n \frac{dn}{dx}$$

where

$$\frac{dn}{dx} = \frac{n(x=L) - x(x=0)}{L} = \frac{10.5 \times 10^{15} - 9.5 \times 10^{15}}{100 \times 10^{-4}} = 1.0 \times 10^{17} \,\mathrm{cm}^{-4}$$

Inserting we get

$$J_n = 1.602 \times 10^{-19} \times 34 \times 1.0 \times 10^{17} = 0.54 \,\mathrm{A/cm^2}$$

which is a current along the positive x-axis.

(c) We can create an opposing drift current by imposing an opposite electric field. We want a positive current, so we apply a electric field which is directed in the positive x-direction. Ignore minority carriers, so we get

$$J_{\rm drift} = q n \mu_n E$$

and assume $n = 10^{16} \,\mathrm{cm}^{-3}$ everywhere. This current must cancel the diffusion current so we have

$$-J_n = J_{\text{drift}} = qn\mu_n E$$

or

$$E = -\frac{J_n}{qn\mu_n} = -\frac{0.54}{1.602 \times 10^{-19} \times 10^{16} \times 1350} = -0.25 \,\mathrm{V/cm}$$

which is a voltage drop of

$$V = EL = -0.25 \times 100 \times 10^{-4} = -2.5 \times 10^{-3} V = -25 \,\mathrm{mV}$$

where the polarity is such that the higher potential is at x = L.

Quantity	Relationship	(for Intrinsic Si at $T = 300 \text{ K}$)
Carrier concentration in p -type silicon (/cm ³)	$p_{p0} \approx N_{\rm A}$ $n_{p0} = n_i^2/N_{\rm A}$	
Junction built-in voltage (V)	$V_0 = V_T \ln \left(\frac{N_A N_D}{n_i^2} \right)$	
Width of depletion region (cm)	$\begin{split} & \frac{x_a}{x_p} = \frac{N_A}{N_D} \\ & W_{dep} = x_a + x_p \\ & = \sqrt[2]{\frac{2\varepsilon_f}{q} \left(\frac{1}{N_A} + \frac{1}{N_D}\right)} (V_0 + V_R) \end{split}$	$\varepsilon_{i} = 11.7\varepsilon_{0}$ $\varepsilon_{0} = 8.854 \times 10^{-14}$ F/cm
Charge stored in depletion layer (coulomb)	$q_I = q \frac{N_{\vec{A}}N_D}{N_A + N_D} A W_{dep}$	
Depletion capacitance (F)	$C_{j} = \frac{\varepsilon_{j}A}{W_{dep}}, C_{j0} = \frac{\varepsilon_{j}A}{W_{dep} _{V_{deo}}}$ $C_{j} = C_{j0} / \left(1 + \frac{V_{R}}{V_{0}}\right)^{\alpha}$ $C_{j} \approx 2C_{j0} \text{ (for forward bias)}$	
Forward current (A)	$I = I_p + I_n$ $I_p = Aqn_{LpN_p}^2 (e^{V/Y_T} - 1)$ $I_n = Aqn_{LpN_n}^2 (e^{V/Y_T} - 1)$	
Saturation current (A)	$I_S = Aq n_i^2 \left(\frac{D_p}{L_p N_D} + \frac{D_n}{L_n N_A} \right)$	
Minority-carrier lifetime (s)	$\tau_p = L_p^2 / D_p \qquad \tau_n = L_n^2 / D_n$	$L_{p^*}L_n = 1 \ \mu \text{m to } 100 \ \mu \text{m}$ $\tau_p, \tau_n = 1 \ \text{ns to } 10^4 \ \text{ns}$
Minority-carrier charge storage (coulomb)	$\begin{array}{llllllllllllllllllllllllllllllllllll$	
Diffusion capacitance (F)	$C_d = \left(\frac{\tau_T}{V_T}\right)I$	

Junction Capacitance The depletion-layer or junction capacitance under forward-bias conditions can be found by replacing V_R with -V in Eq. (3.57). It turns out, however, that the accuracy of this relationship in the forward-bias region is rather poor. As an alternative, circuit designers use the following rule of thumb: (3.70) **3.34** A diode has $N_i = 10^{17} (\text{cm}^3, N_D = 10^{16} (\text{cm}^3, n_i = 1.5 \times 10^{10} (\text{cm}^3, L_n = 5 \, \text{µm}, L_n = 10 \, \text{µm}, A = 3500 \, \text{µm}^3, D_i$ (in the *n* region) = 10 cm $^{-3} N_i$, and D_i (in the *n* region) = 10 cm $^{-3} N_i$. The diode is forward biased and conducting a current $I = 0.1 \, \text{mA}$. Calculate: (a) I_{is} (b) the forward-bias voltage Y_i (c) the component of the current I due to hole injection and that due to electron injection across the junction. (d) T_i and T_i ; (e) the cross hole injection Ω_i , and the access factor otherge in the *p* region \mathcal{O}_i , and the access factor otherge in the *p* region \mathcal{O}_i , and the textess factor otherge in the *p* region \mathcal{O}_i , and hence \mathcal{M}_i (a) $12 \times 10^{-15} \, \text{ A}_i$ (b) $0.616 \, \text{V}_i$ (c) $91.7 \, \text{µA}_i$ $8.3 \, \text{µA}_i$ (d) $25 \, \text{ns}_i$ (f) $10 \, \text{pF}_i$ Values of Constants and Parameters (for Intrinsic Si at T = 300 K) $q = 1.60 \times 10^{-19}$ coulomb $B = 5.4 \times 10^{31} / (\text{K}^3 \text{cm}^6)$ $E_G = 1.12 \text{ eV}$ $k = 8.62 \times 10^{-5} \text{eV/K}$ $n_i = 1.5 \times 10^{10} / \text{cm}^3$ $\mu_p = 480 \text{ cm}^2/\text{V}\cdot\text{s}$ $D_p = 12 \text{ cm}^2/\text{s}$ $D_n = 34 \text{ cm}^2/\text{s}$ $C_j \simeq 2C_{j0}$

For easy reference, Table 3.2 provides a listing of the important relationships that describe the physical operation of pn junctions. μ_p and μ_n decrease with the increase in doping concentration $\mu_n = 1350 \text{ cm}^2/\text{V}\cdot\text{s}$ $V_T = kT/q$ TABLE 3.2 Summary of Important Equations for *pn*-Junction Operation $J_{avift} = q(p\mu_p + n\mu_n)E$ $\rho \,=\, 1/[q(p\mu_p+n\mu_n)]$ $n_i^2 = BT^3 e^{-E_G/kT}$ $\frac{D_n}{\mu_n} = \frac{D_p}{\mu_p} = V_T$ $J_p = -qD_p \frac{dp}{dx}$ $J_n = qD_n \frac{dn}{dx}$ Relationship 3.7.6 Summary Relationship between mobility and diffusivity Carrier concentration in intrinsic silicon (/cm³) Drift current density (A/cm²) Diffusion current density (A/cm²) Resistivity (Q·cm) Quantity

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 $\approx 25.8 \text{ mV}$

 $P_{n0} = n_i^2/N_D$

 $n_{n0} \simeq N_D$

Cartier concentration in n-type silicon (/cm³)

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